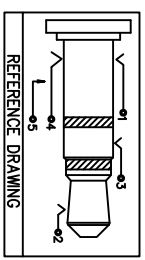
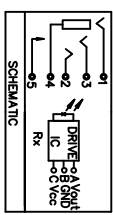
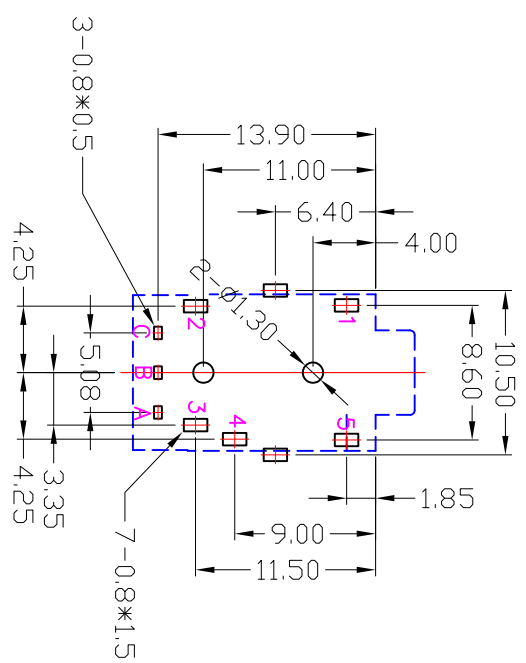
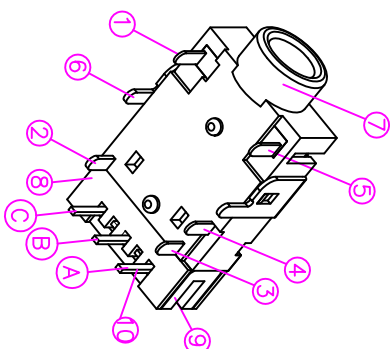
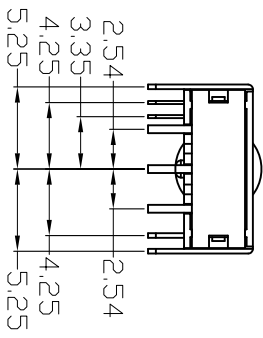
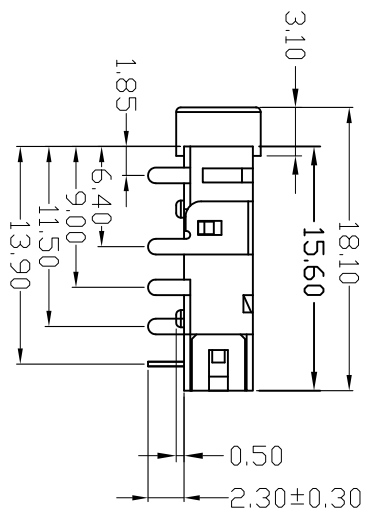
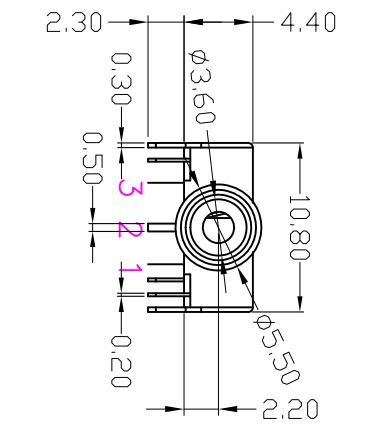
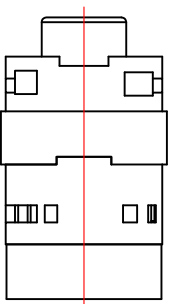


REV	DATE	DESCRIPTION



基板下參考圖(公差±0.3)
PCB LAYOUT(Tol.±0.3)

ITEM	DESCRIPTIONS	MATERIAL	FINISH	Q'TY	NOTE
⑩	DRIVE IC(RX)			1	
⑨	COVER	HIGH-TEMP PLASTIC	BLACK	1	
⑧	CASE	HIGH-TEMP PLASTIC	BLACK	1	
⑦	HOUSING	HIGH-TEMP PLASTIC	BLACK	1	
⑥	SHIELDING	COPPER ALLOY	NI	1	60 μ min
⑤	DETECTOR	PHOSPHOR BRONZE	AU	1	
④	GND	PHOSPHOR BRONZE	AU	1	Au 1 μ ' &
③	RIGHT CHANNEL	PHOSPHOR BRONZE	AU	1	NI 50 μ ' min
②	LEFT CHANNEL	PHOSPHOR BRONZE	AU	1	
①	DETECTOR	PHOSPHOR BRONZE	AU	1	

PART NAME	光纤连接器	
PART NUMBER	DLR11M1	
TOLERANCE	±0.20	
APPROVED	UNIT	mm
CHECK	MATERIAL	DATE
DRAWING	SCALE	2011/03/01
	FIT	PAGE
		1/1

XYFWCN

Third Angle Projection